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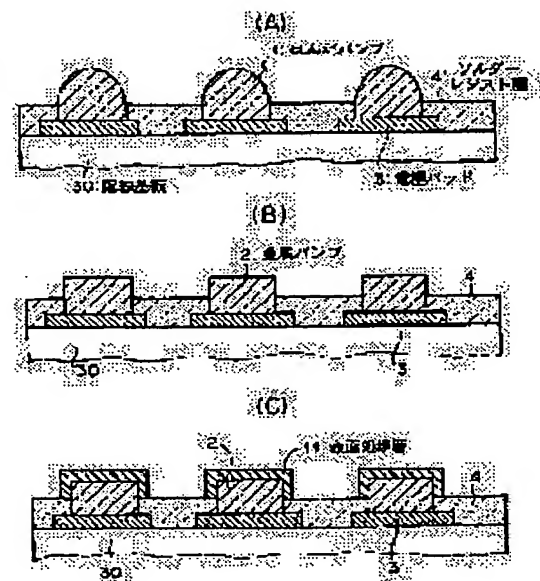
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(54) MANUFACTURE OF MOUNTING SUBSTRATE WITH SOLDER RESIST LAYER FORMED WITH BUMP ON ELECTRODE PAD**(57)Abstract:**

PROBLEM TO BE SOLVED: To provide a mounting substrate, wherein the desired amount of solder paste is supplied on each electrode pad to form a solder bump of desired size, while the possibility for the occurrence a solder bridge between adjoining bumps is less, even with finer electrode pad array pitch.

SOLUTION: A solder resist layer 4 is formed on a wiring board 30 comprising a plurality of electrode pads 3 formed on the surface, a dry film is formed on its surface, the solder resist layer 4 and the dry film are provided with an opening, the openings are filled with a solder paste for reflow, so that the solder paste is melted and solidified, forming a solder bump 1. Then the dry film is removed, so that the solder resist layer 4 is formed between the electrode parts comprising the electrode pad 3 with the solder bump 1, where the top part of the solder bump 1 is above the surface of the solder resist layer 4.

**LEGAL STATUS**

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